

# ACCESSORIES

## WAFER MAPPING SENSORS

### IMS-MDW1

- LED light source
- measuring distance 45 mm (1.75")
- PNP / NPN switchable



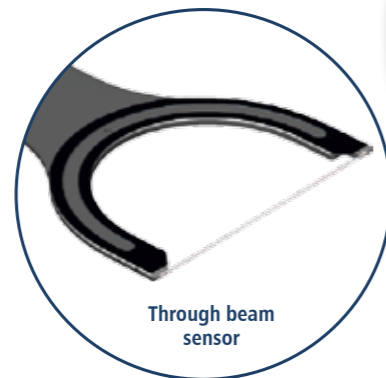
IMS-MDW1

### PD 45

- laser (class 2) light source
- measuring distance 200 mm or 300 mm
- small laser dot and housing



PD 45



Through beam sensor

### THROUGH BEAM SENSOR

- optional to reflective Sensor
- integrated in endeffector

## FLIP MODULE IFM-300-3

- precise wafer flipping by adjustable mechanical stops
- universal endeffector adapter
- adjustable hard stop damping
- adjustable flip speed
- option: lateral mapping sensor



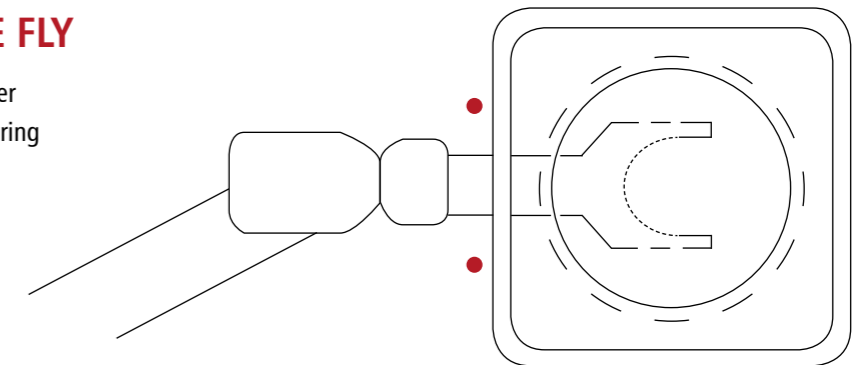
## YAW AXIS

- 4th axis upgrade for a three-axis system (yaw angle in the Z axis)
- in-line handling of rectangular substrates
- in-line handling without a linear track
- upgrade for existing isel HD wafer handling robots



## ALIGNMENT ON THE FLY

- wafer centering without prealigner
- offset capturing and centering during robot at GET or PUT movement
- no alignment station necessary
- time efficient wafer centering



● = laser sensors

## ENDEFFECTOR CHANGER

(Advanced controller only)

- full automatically endeffector changing system
- software endeffector management
- for all endeffector types

